

SOT826-1

plastic low profile fine-pitch ball grid array package; 73 balls;
body 7 x 7 x 0.9 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFPGA73
Package type industry code	LFPGA73
Package style descriptive code	LFPGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	5-8-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	[tbd]	-	1.3	1.3	mm
A ₂	package height	0.8	-	0.9	1	mm
n ₂	actual quantity of termination	-	-	73	-	



2. Package outline

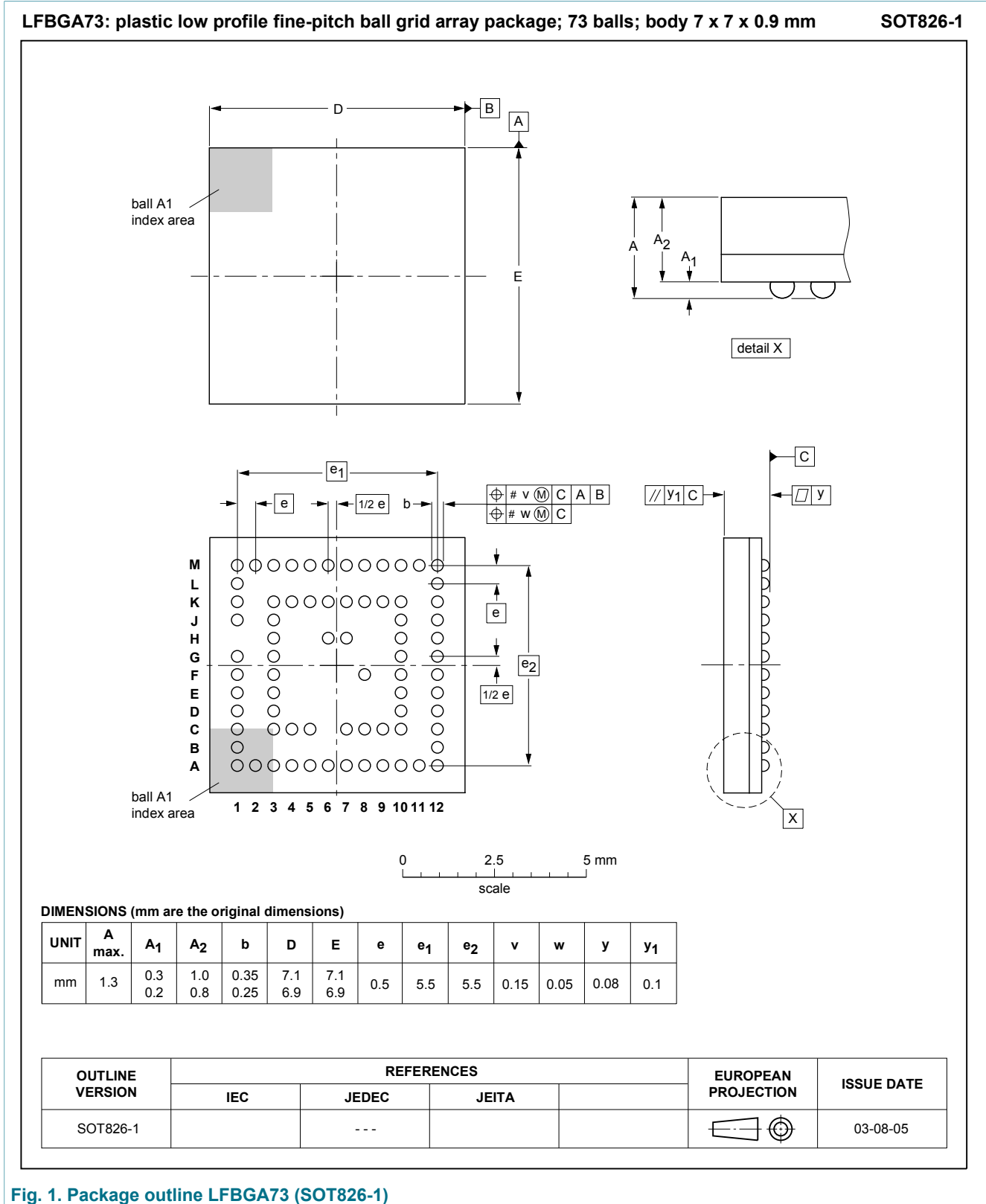


Fig. 1. Package outline LFBGA73 (SOT826-1)

3. Soldering

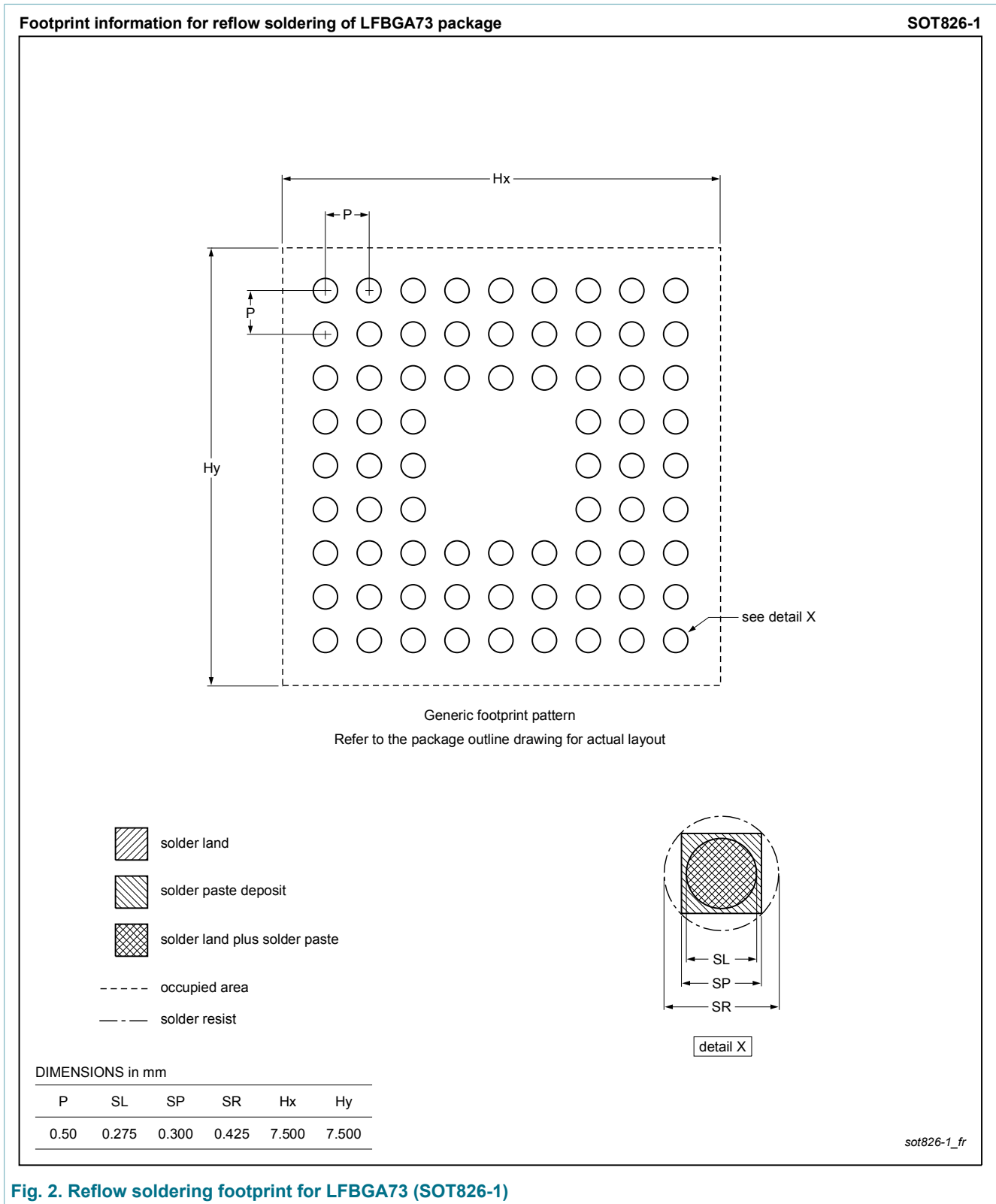


Fig. 2. Reflow soldering footprint for LFBGA73 (SOT826-1)

4. Legal information

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